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Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

On

6-1-04

TOWNSEND and TOWNSEND and CREW LLP

By:

Risa Kusen

PATENT

Docket No.: 018865-004210US
Client Ref. No.: 17732.13420.003
(divisional)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Joshi et al.

Application No.: 10/607,633

Filed: June 27, 2003

For: FLIP CHIP IN LEADED MOLDED
PACKAGE AND METHOD OF
MANUFACTURE THEREOF

Examiner: Leonardo Andujar

Art Unit: 2826

RESPONSE TO RESTRICTION
REQUIREMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the Office Action mailed May 7, 2004, the Examiner restricts the claims into two Groups, Group I (claims 1-5) and Group II (claims 7-17).

In response to the Office Action, Applicants elect Group II, claims 7-17, drawn to a method of manufacturing a semiconductor device, for prosecution on the merits, with traverse.



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PATENT

An Office Action on the merits is respectfully requested.

Respectfully submitted,

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Reg. No. 40,456

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